Exhibition

ARELIS is a key industrial reference for microwave and RF projects. The group offers value added services from the design and manufacturing to the technology transfer of sub-systems dedicated to detection, guidance and communications applications, whether civil or military. Its solutions are developed for defense, security, aeronautics, spatial telecoms and broadcast industries. With the acquisition of Thomson Broadcast, Arelis is one of the world's leading players in digital television and radio transmission. Leader and partner of research and development programs, Arelis strongly contributes to multimode amplifier development, to the components miniaturisation with the integration in inner layers or to the development of SDR platforms. Forward-looking, it heavily invests in research and development for the creation of off-grid energy systems with long-term energy storage capacities.
More about Arelis : http://www.arelis.com

BT-Electronics offers a wide range of products and equipment for RF & Microwave applications.
So the products proposed are:
packages and lids used for the component assembly , as well as preforms, ribbons and soldering balls from all alloys, bonding tools, wires, glues, resins and adhesives, Passive components such as low-pass filters with different types of design.
Equipment offered are: test devices and stations, cube or storage cabinet with nitrogen, Gross leak controllers and a whole range of hot plates.
Ask us, we will do everything to satisfy you!

Materion Advanced Materials Group is an industry leader in providing durable and best-cost solutions for ceramic packages and hermetic cover/lids for the microelectronics industry. We offer a comprehensive portfolio of packaging materials in precious or non-precious material and can customize innovative electronic package materials to satisfy your unique needs. Our high-reliability packaging also supports most configurations, applications and volume requirements. Because of our industry expertise, extensive global manufacturing capabilities and R&D proficiency, we are able to meet customers' packaging requirements today and partner with them to meet future challenges.

Schunk Hoffmann Carbon Technology is a world leader in the development and production of carbon and graphite materials and components for the automotive and railway industries. Additionally, we provide two graphite-based solutions for the electronics cooling industry.
The composite material, Aluminium Graphite (ALG), combines the low coefficient of thermal expansion and density of graphite with the excellent thermal properties of aluminium to create an ideal thermal management material for high-reliability applications. With its ready machinability, we can produce customized ALG parts such as flanges or housings for power amplifiers in various quantities with a range of platings.
Our new phase change composite material, Latent Heat Carbon, is a novel approach to latent heat storage units. It is ideally suited to buffering temperature peaks. Its Expand to Shape production process allows for custom designs at an attractive cost that can be tailored to individual customer needs.

Torrey Hills Technologies, LLC is a leader in developing and delivering quality yet extremely affordable materials, fabricated parts, and equipment for multiple industries. The company's core business includes refractory metal heat sinks (CuW, CuMo, CMC, CPC), fabricated microelectronics packaging components, molybdenum, tungsten and their alloy materials, and furnace equipment for electronics and solar cell industry.

Exhibitors, we have some more table top for you…

How to register to RaMP

Two options to register to the event:

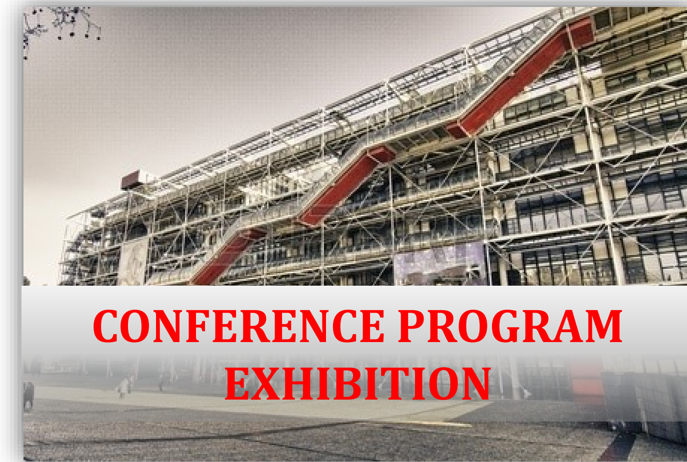
→ **Go on the dedicated website:** *www.france.imapseurope.org/index.php/registration-ramp*

→ **Send a mail to:** *imaps.france@imapsfrance.org*

NEXT IMAPS EVENTS

- **MINaPAD in Grenoble May 17,18 2017**
- **EMPC 2017 in Varsaw September 11, 12 2017**
- **ATW Medical in Lyon November 28, 29 2017**

INTERNATIONAL MICROELECTRONICS ASSEMBLY and PACKAGING SOCIETY



April 26, 27 2017
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2017 Conference Program - Exhibition

General Chairs: B Braux (Imaps France) and K Kuang (Torrey Hills Technologies)

WEDNESDAY, APRIL 26

09:00 Registration / Welcome coffee

10:00 Opening Remarks
Brigitte Braux (IMAPS France), **Ken Kuang**, Torrey Hills Technologies, LLC

10:15 Keynote
- A Numerical Analysis of Packaging Structures and Parameters of Quartz Crystal Resonators
Prof. Ji Wang (Ningbo University, China)

SESSION PA-1: RF Packaging Assembly

11:00 Die-attach reliability of Gold Tin (AuSn) soldered GaN devices in temperature cycle tests.
Roelof van der Berg, Arne Heessels (Ampleon, The Netherlands)

11:30 Advanced Hermetic Glass Encapsulation
Beat Scheidegger (Glenca Tec AG, Switzerland)

12:00 QFN-based Packaging Concepts for Millimeter Wave Transceivers
Mario Pauli, Thomas Zwick (Karlsruher Institut für Technologie, KIT, Germany)

12:30 Lunch Break

SESSION PA-2: RF Packaging Assembly

14:00 Wireless communication & Virtual SIM Card
Simon Guo (Ucloudlink, Benelux)

14:30 Three-dimensional step covered interconnection method for HySiF (Hybrid system in flexible)
S.I. Rhee, Yongjin Kim, Jae Hak Lee, Joon Yub Song (Institute of Machinery ad Materials, USA)

15:00 Non-hermetic Package for MetOp-SG V-band Front-Ends
Thibaut Decoopman, Yann de Thonel d'Orgeix, Robert Farré, Alain Lemasson, Nadine Martin, Jacques Tailhades (Airbus Defence and Space, France)

15:30 Coffee Break

SESSION STD1 : Simulation / Thermal / Design

16:00 mm-wave Technologies and Components for 5G Applications
Liam Devlin (Plextek RFI, United Kingdom)

16:30 A compact high power waveguide amplifier in GaN technology
Markus Mayer, Guillaume Pees-Martin, Claudio Pires-Carvalho, Francois Parickmiler (Arelis, France)

17:00 New RFID Solutions Providing Additional Functions for Tracing and Tracking of Items
Dr.-Ing. Werner John, Tobias John; Frank Jaeger (SIL System Integration Laboratory, Germany)

19:30 **Social event:**
Dinner in "L'Ambassade d'Auvergne" restaurant
22, Rue du Grenier Saint-Lazare, 75003 Paris

THURSDAY, APRIL 27

09:15 Opening Remarks

SESSION STD2: Simulation / Thermal / Design

09:30 Scalability of beam forming. How to build large antenna
Marcel Wieland (Globalfoundries, Germany), Andy Heinig (IIS), Matthias Boettger (IZM), Christian Götze (GF), Uwe Maaß(IZM)

10:00 SUPA – Smart Universal Power Antenna
Dr.-Ing. Christian Hedayat, Maik-Julian Bücker (Fraunhofer ENAS, Germany)

10:30 Coffee break

SESSION MTL1: Materials

11:00 Solder-TIMs (Thermal Interface Materials) for Improved Thermal Management in Power Electronics
Graham Wilson, Karthik Vijay (Indium, United Kingdom)

11:30 Conductive Die Attach Solutions for Thinner Wafer and Higher Power Applications
Ruud de Wit, Tony Winster (Henkel Electronic Materials NV ,Belgium)

12:00 Keynote
- LTCC-based Modules for Smart ComSat-Applications
Prof. Dr.-Ing. Jens Müller (Ilmenau University of Technology, Germany)

12:45 Lunch break

SESSION MTL2: Materials

14:15 Direct Bond Copper for RF Packaging
Richard Koba, Chee Kong Lee, Weichuan Goh , SiYee Chin (Materion, USA)

14:45 On the Integration of Inductors in High-Density Fan-Out Wafer Level Packages
Dr.-Ing. Christian Tschoban (Fraunhofer IZM , Germany)

15:15 Dielectric Characterisation Techniques of LTCC Materials
Dr.-Ing. Alexander Schulz, S. Spira, M. Hein, J. Müller (Ilmenau University of Technology, Germany)

15:45 Graphene in CuMo / CuW heatspreaders
Brian Kennedy (Kennedy Labs , Canada), Ken Kuang, Torrey Hills Technologies, LLC

16:15 Closing Remarks Farewell
Brigitte Braux (IMAPS France), Ken Kuang, Torrey Hills Technologies, LLC